**FAIRCHILD**
SEMICONDUCTOR®

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# FSA2567 — Low-Power, Dual SIM Card Analog Switch

## Features

- Low On Capacitance for Data Path: 10pF Typical
- Low On Resistance for Data Path: 6Ω Typical
- Low On Resistance for Supply Path: 0.4Ω Typical
- Low Power Consumption: 1µA Maximum
  - 15µA Maximum $I_{CCT}$ Over Expanded Voltage Range ($V_{IN}$=1.8V, $V_{CC}$=4.3V)
- Wide -3db Bandwidth: > 160MHz
- Packaged in:
  - Pb-free 16-Lead MLP
  - Pb-free 16-Lead UMLP (1.8 x 2.6mm)
- 3kV ESD Rating, >12kV Power/GND ESD Rating

## Applications

- Cell phone, PDA, Digital Camera, and Notebook
- LCD Monitor, TV, and Set-Top Box

## IMPORTANT NOTE:

For additional performance information, please contact analogswitch@fairchildsemi.com.

## Description

The FSA2567 is a bi-directional, low-power, dual double-pole, double-throw (4PDT) analog switch targeted at dual SIM card multiplexing. It is optimized for switching the WLAN-SIM data and control signals and dedicates one channel as a supply-source switch.

The FSA2567 is compatible with the requirements of SIM cards and features a low on capacitance ($C_{ON}$) of 10pF to ensure high-speed data transfer. The $V_{SIM}$ switch path has a low $R_{ON}$ characteristic to ensure minimal voltage drop in the dual SIM card supply paths.

The FSA2567 contains special circuitry that minimizes current consumption when the control voltage applied to the SEL pin is lower than the supply voltage ($V_{CC}$). This feature is especially valuable in ultra-portable applications, such as cell phones; allowing direct interface with the general-purpose I/Os of the baseband processor. Other applications include switching and connector sharing in portable cell phones, PDAs, digital cameras, printers, and notebook computers.

## Ordering Information

| Part Number | Top Mark | Operating Temperature Range | Package |
|---|---|---|---|
| FSA2567MPX | FSA2567 | -40 to +85°C | 16-Lead, Molded Leadless Package (MLP) Quad, JEDEC MO-220, 3mm Square |
| FSA2567UMX | GX | -40 to +85°C | 16-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 1.8 x 2.6mm |

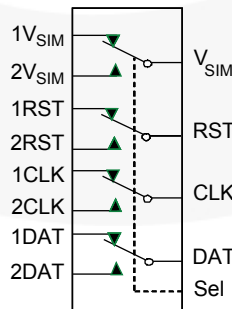All packages are lead free per JEDEC: J-STD-020B standard.



**Figure 1.   Analog Symbol**

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